3.3V Dual LVTTL/LVCMOS to Differential LVPECL Translator

The MC100LVELT22 is a dual LVTTL/LVCMOS to differential LVPECL translator. Because LVPECL (Low Voltage Positive ECL) levels are used, only +3.3 V and ground are required. The small outline 8-lead package and the low skew, dual gate design of the LVELT22 makes it ideal for applications which require the translation of a clock and a data signal.

- 350 ps Typical Propagation Delay
- <100 ps Output-to-Output Skew
- ESD Protection: >4 KV HBM, >200 V MM
- Flow Through Pinouts
- The 100 Series Contains Temperature Compensation
- LVPECL Operating Range: V_{CC}= 3.0 V to 3.8 V with GND= 0 V
- When Unused TTL Input is left Open, Q Output will Default High
- Meets or Exceeds JEDEC Spec EIA/JESD78 IC Latchup Test
- Moisture Sensitivity Level 1
 For Additional Information, see Application Note AND8003/D
- Flammability Rating: UL-94 code V-0 @ 1/8", Oxygen Index 28 to 34
- Transistor Count = 164 devices



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MARKING DIAGRAMS*



SO-8 D SUFFIX CASE 751





TSSOP-8 DT SUFFIX CASE 948R



A = Assembly Location

L = Wafer Lot

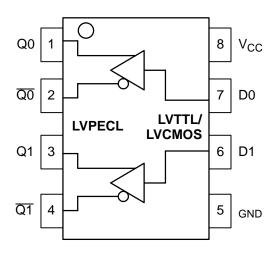
Y = Year

W = Work Week

*For additional information, see Application Note AND8002/D $\,$

ORDERING INFORMATION

Device	Package	Shipping
MC100LVELT22D	SO-8	98 Units / Rail
MC100LVELT22DR2	SO-8	2500 / Reel
MC100LVELT22DT	TSSOP-8	98 Units / Rail
MC100LVELT22DTR2	TSSOP-8	2500 / Reel



PIN DESCRIPTION

PIN	FUNCTION
Qn, Qn	LVPECL Differential Outputs
D0, D1	LVTTL/LVCMOS Inputs
V _{CC}	Positive Supply
GND	Ground

Figure 1. 8-Lead Pinout (Top View) and Logic Diagram

MAXIMUM RATINGS (Note 1.)

Symbol	Parameter	Condition 1	Condition 2	Rating	Units
V _{CC}	Positive Power Supply	GND = 0 V		7	V
VI	Input Voltage	GND = 0 V	$V_{I} \leq V_{CC}$	7	V
l _{out}	Output Current	Continuous Surge		50 100	mA mA
TA	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ_{JA}	Thermal Resistance (Junction to Ambient)	0 LFPM 500 LFPM	8 SOIC 8 SOIC	190 130	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction to Case)	std bd	8 SOIC	41 to 44 ± 5%	°C/W
$\theta_{\sf JA}$	Thermal Resistance (Junction to Ambient)	0 LFPM 500 LFPM	8 TSSOP 8 TSSOP	185 140	°C/W
θ_{JC}	Thermal Resistance (Junction to Case)	std bd	8 TSSOP	41 to 44 ± 5%	°C/W
T _{sol}	Wave Solder	<2 to 3 sec @ 248°C		265	°C

^{1.} Maximum Ratings are those values beyond which device damage may occur.

LVPECL DC CHARACTERISTICS V_{CC}= 3.3 V; GND= 0.0 V (Note 1.)

			–40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
Icc	Power Supply Current			28			28			29	mA
V _{OH}	Output HIGH Voltage (Note 2.)	2275		2420	2275		2420	2275		2420	mV
V _{OL}	Output LOW Voltage (Note 2.)	1490		1680	1490		1680	1490		1680	mV

NOTE: Devices are designed to meet the DC specifications shown in the above table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfpm is maintained.

1. Output parameters vary 1:1 with V_{CC}. V_{CC} can vary ±0.15V.

- 2. Outputs are terminated through a 50 ohm resistor to $V_{\mbox{CC}}$ -2 volts.

LVTTL/LVCMOS INPUT DC CHARACTERISTICS $V_{CC} = 3.3V$; $T_A = -40$ °C to 85°C (Note 1.)

Symbol	Characteristic	Min	Тур	Max	Unit	Condition
I _{IH}	Input HIGH Current			20	μΑ	V _{IN} = 2.7V
I _{IHH}	Input HIGH Current			100	μΑ	$V_{IN} = V_{CC}$
I _{IL}	Input LOW Current			-0.2	mA	V _{IN} = 0.5V
V _{IK}				-1.2	V	I _{IN} = -18mA
V _{IH}	Input HIGH Voltage	2.0			V	
V_{IL}	Input LOW Voltage	·		0.8	V	

^{1.} V_{CC} can vary ± 0.15 V.

AC CHARACTERISTICS V_{CC} = 3.3 V; GND= 0.0 V (Note 1.)

			–40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f _{max}	Maximum Toggle Frequency		TBD			TBD			TBD		GHz
t _{PLH}	Propagation Delay (Note 2.)	200	350	600	200	350	600	200	350	600	ps
t skew	Skew Output-to-Output Part-to-Part		30	100 400		30	100 400		30	100 400	ps
t _{JITTER}	Cycle-to-Cycle Jitter		TBD			TBD			TBD		ps
t /t r f	Output Rise/Fall Time (20-80%)	200		550	200		500	200		500	ps

- 1. V_{CC} can vary ± 0.15 V. 2. Specifications for standard TTL input signal.

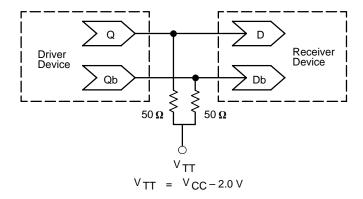


Figure 1. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020 – Termination of ECL Logic Devices.)

Resource Reference of Application Notes

AN1404 – ECLinPS Circuit Performance at Non–Standard V_{IH} Levels

AN1405 – ECL Clock Distribution Techniques

AN1406 – Designing with PECL (ECL at +5.0 V)

AN1503 – ECLinPS I/O SPICE Modeling Kit

AN1504 – Metastability and the ECLinPS Family

AN1560 – Low Voltage ECLinPS SPICE Modeling Kit

AN1568 - Interfacing Between LVDS and ECL

AN1596 – ECLinPS Lite Translator ELT Family SPICE I/O Model Kit

AN1650 – Using Wire–OR Ties in ECLinPS Designs

AN1672 – The ECL Translator Guide

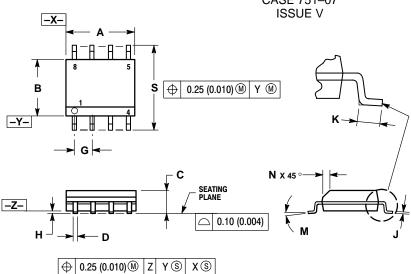
AND8001 - Odd Number Counters Design

AND8002 - Marking and Date Codes

AND8020 - Termination of ECL Logic Devices

PACKAGE DIMENSIONS

SO-8 **D SUFFIX** PLASTIC SOIC PACKAGE CASE 751-07



NOTES:

- NOTES:

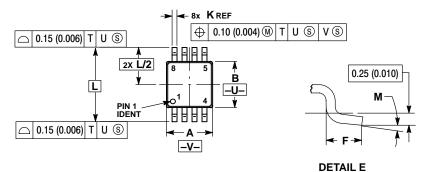
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

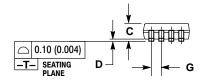
	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	4.80	5.00	0.189	0.197	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.053	0.069	
D	0.33	0.51	0.013	0.020	
G	1.27	7 BSC	0.050 BSC		
Н	0.10	0.25	0.004	0.010	
J	0.19	0.25	0.007	0.010	
K	0.40	1.27	0.016	0.050	
M	0 °	8 °	0 °	8 °	
N	0.25	0.50	0.010	0.020	
5	5.80	6.20	0.228	0 244	

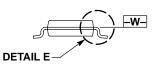
PACKAGE DIMENSIONS

TSSOP-8 **DT SUFFIX**

PLASTIC TSSOP PACKAGE CASE 948R-02 ISSUE A







NOTES:

- 11ES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED
- FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIN	IETERS	INC	HES
DIM	MIN MAX MIN		MIN	MAX
Α	2.90	3.10	0.114	0.122
В	2.90	3.10	0.114	0.122
С	0.80	1.10	0.031	0.043
D	0.05	0.15	0.002	0.006
F	0.40	0.70	0.016	0.028
G	0.65	BSC	0.026 BSC	
K	0.25	0.40	0.010	0.016
L	4.90	4.90 BSC		BSC
M	0°	6 °	0°	6°



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